

12/24/94 SUPERSEDES 12/24/93

ANALYST:

NAME P/N QTY	CRIT	FAILURE MODE & CAUSES	FAILURE EFFECT	RATIONALE FOR ACCEPTANCE
DCM ELECTRONICS, ITEM 350 ----- SV792291-27 (1)	2/2	SSOPM17: Battery current sense circuit output drifts high. CAUSE: Overheating or faulty electrical connection.	END ITEM: Measured battery current higher than actual current. OFE INTERFACE: Battery ampere hour accumulator reads high. MISSION: Terminate EVA. CREW/VEHICLE: None.	A. Design - Semiconductor failure is minimized through the use of high reliability components. Established reliability capacitors (Level S) and resistors (Level R) are used and are qualified to the requirements of MIL-S-19500 and receive the burn-in of JANTXV level parts per the applicable methods, 1038, 1039, and 1040, of MIL-STD-750. The electronic components are operating within the power derating requirements of SVHS 7004. The printed circuit boards are polyimide per MIL-P-13949 Type G1 and manufactured per SN-P-0006. Parts mounting and soldering is per MSFC-870-136 and NHB5300. 4(3A-1). The board assemblies are hard mounted to the DCM case to provide a thermal transfer path between the board sinks and the case to direct heat away from the electronic components. The board assemblies are also conformal coated per MIL-A-46146 (Dow Corning RTV 3140) for environmental protection. All wiring used in the DCM is M22759/11 (teflon insulated). Soldering is per NHB5300. 4 (3A-1) and wire crimping is per SVHS 4909 (based on MSC-SPEC-Q-1A). All wires are strain relieved. Electrical connectors are environmentally sealed to prevent damage due to contamination and humidity. B. Test - In-Process Test - The DCM electronics assembly is tested during initial build-up; at the board assembly level, after the PC boards have been interwired after installation of the boards and wiring, and after installation of the front cover. These tests consist of continuity through the switches and wiring, voltage checks, functional check of all current limiters, and full operation of the DCM electronics. The tests insure proper operation of the DCM electronics. PDA Test - Vibration testing per SEMU-60-015 followed by continuity and full function, testing verifies the integrity of the solder joints and crimp connections in the DCM. The random vibration level for this test is 6.6 grms for a duration of 1 minute per axis for each of the three orthogonal axes.(JSC SPEC SP-T-0023). Thermal vacuum testing followed by full functional electrical testing per SEMU-60-015 also verifies the solder

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	2/2	350PM17:		<p>Joints as well as the acceptability of the components. The DCM is placed in a vacuum chamber 1×10^{-3} torr. The DCM case temperature is cycled 3 times from 70 to 130 degree F. At the end of the third cycles, the temperature is held between 130 and 135 degree F for a minimum of four hours. The BCM display must remain on throughout the test. This verifies proper transfer of heat from the electronics to the BCM case of prevent overheating of components.</p> <p>Certification Test - The Liquid Crystal Display version of the BCM electronics assembly (Item 350, SV792291-7), as part of the full BCM Item 300 (Items 350 and 385 combined), was successfully subjected to levels of vibration and shock equivalent to those experienced over a fifteen year (15) year life.</p> <p>Random Flight Vibration 1.625 grms. 48 min/axis Sinusoidal Flight 1 grms. 5-35 Hz ea. Vibration axis Design Shock 6.5 grms. 11 ms/peak</p> <p>The LED display version of the BCM electronics Assembly (Item 350, SV792291-5) was subjected to certification testing between June and August of 1986 with the exception of EMI which occurred in September of 1985. The testing verified the basic integrity and flight worthiness of the redesign DCM configuration (Item 300, SV792294). The Item 350 completed qualification vibration (7.0 grms, 6 minutes per axis) as a separate item, and structural vibration (1.625 grms, 48 minutes per axis), and shock testing as part of the full DCM Item 300 (Item 350 combined with Item 385). The DCM/300 also completed the four hour thermal vacuum certification at 135 degree F and storage temperature testing at 33 degree F. No Class 1 EC's have been incorporated into this version of the DCM since certification was completed.</p> <p>C. Inspection - 100% inspection of all soldering (PC boards and wiring) by Hamilton Standard QA and BCAS QA. All board assemblies are inspected for damage and contamination. All wiring is inspected for damage, nicks in the insulation, wear, and strain relief.</p>

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	2/2	350FH17:		
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The DCN is internally inspected after installation of the circuit boards and wiring to insure no damage has occurred during assembly.

D. Failure History -
None.

E. Ground Turnaround -
None for minor drift. Severe drift would cause a false high current warning during tests per FEMU-R-001, Transducer and DCN Gauge Calibration Check.

F. Operational Use -
Crew Response - PreEVA: If failure can be linked to sensor, continue EVA operations. EMU go for EVA.
Otherwise, consider third EMU if available.
EVA: Conclude EVA. Rely on low battery voltage warning message.

Training -

Standard EMU training covers this failure mode.

Operational Considerations -

For single failure, no constraints. EVA checklist procedures verify hardware integrity and systems operational status prior to EVA.

Flight rules define go/no go criteria related to battery power. Real Time Data System allows ground monitoring of EMU systems.